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(54) Title: PRINTED CIRCUIT BOARD AUTOMATED LAYUP SYSTEM

(57) Abstract: An apparatus to automatically place layers of a printed circuit board on a fixture includes a robotic device having a base that is secured to a surface, an upright column that extends upwardly from the base, and a movable arm rotatably coupled to the upright column. The movable arm is configured to rotate about a vertical axis defined by the upright column. The movable arm is further configured to rotate from a position in which the movable arm is disposed over a laminate sheet fixture and to pick up a laminate sheet to a position in which the movable arm is disposed over a board layup fixture to deposit the laminate sheet in the board layup fixture, and from a position in which the movable arm is disposed over a bond film fixture and to pick up a bond film to a position in which the movable arm is disposed over the board layup fixture to deposit the bond film in the board layup fixture.

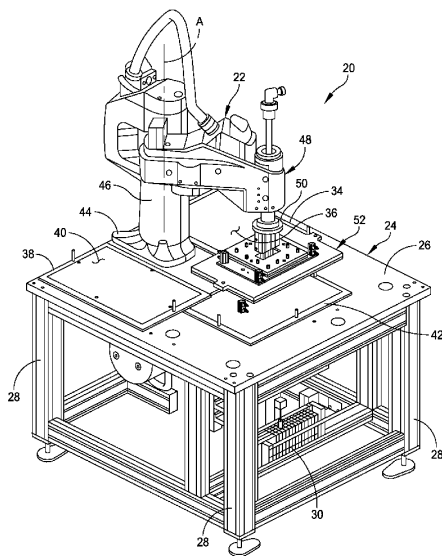


FIG. 2

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Declarations under Rule 4.17:

- *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))*
- *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))*

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